

with resin is defined.

104. The mold for fabricating the semiconductor device as claimed in claim 103, further comprising an excess resin removing mechanism provided in the mold used in a resin sealing step,

wherein the excess resin removing mechanism removes excess resin and controls a pressure applied to the sealing resin in the mold.

105. The mold for fabricating the semiconductor device as claimed in claim 103, further comprising an attachment/detachment mechanism which attaches the substrate to a position of the first half body and detaches the substrate therefrom.

106. The mold for fabricating the semiconductor device as claimed in claim 105, wherein the attachment/detachment mechanism comprises:

a porous member arranged in the position of the first half body onto which the substrate is loaded; and

an intake/exhaust device performing a gas suction and supply process for the porous member.

107. The mold for fabricating the semiconductor device as claimed in claim 103, wherein an area enclosed by the second half body is wider than an area of an upper portion of the first half body in a state in which the cavity is formed.